

PRELIMINARY AMENDMENT

Serial Number: 10/608519

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Title: THERMAL INTERFACE APPARATUS, SYSTEMS, AND FABRICATION METHODS (as amended)

Assignee: Intel Corporation

Page 2

Dkt: 884.847US1 (INTEL)

IN THE TITLE

Please amend the title as stated below:

THERMAL INTERFACE APPARATUS, SYSTEMS, AND FABRICATION METHODS

Conclusion

The Examiner is invited to telephone Applicants' representative, Mark Muller at (210) 308-5677, or the undersigned to facilitate prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully Submitted,

RAJEN C. DIAS ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
Attorneys for Intel Corporation  
P.O. Box 2938  
Minneapolis, Minnesota 55402  
(612) 349-9592

Date Sept. 8, 2003 By Ann M. McCrackin  
Ann M. McCrackin  
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR § 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelop addressed to: M/S Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 8 day of September, 2003.

Name KACIA LEE Signature Kacia Lee